Power MOSFET 40 V, 0.67 mΩ, 370 A, Single N–Channel

Features

- Small Footprint (5x6 mm) for Compact Design
- Low R_{DS(on)} to Minimize Conduction Losses
- Low Q_G and Capacitance to Minimize Driver Losses

0500

- NVMFS5C404NLWF Wettable Flank Option for Enhanced Optical Inspection
- AEC-Q101 Qualified and PPAP Capable

• These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant



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V _{(BR)DSS}	R _{DS(ON)} MAX	I _D MAX
40 V	0.67 mΩ @ 10 V	070 4
40 V	1.0 mΩ @ 4.5 V	370 A

MAXIMUM RATINGS	$(1_{\rm J} = 25^{\circ})$	uniess otherv	vise noted)	-	
Parameter			Symbol	Value	Unit
Drain-to-Source Voltage			V _{DSS}	40	V
Gate-to-Source Voltage			V _{GS}	±20	V
Continuous Drain	Steady State	$T_{C} = 25^{\circ}C$	۱ _D	370	А
Current R _{θJC} (Notes 1, 3)		T _C = 100°C		260	
Power Dissipation		$T_{C} = 25^{\circ}C$	PD	200	W
R _{θJC} (Note 1)		$T_{C} = 100^{\circ}C$		100	
Continuous Drain Current $R_{\theta JA}$ (Notes 1, 2, 3)	Steady State	$T_A = 25^{\circ}C$	I _D	52	А
		$T_A = 100^{\circ}C$		37	
Power Dissipation		T _A = 25°C	PD	3.9	W
$R_{\theta JA}$ (Notes 1 & 2)		$T_A = 100^{\circ}C$		1.9	
Pulsed Drain Current	$T_{A} = 25$	°C, t _p = 10 μs	I _{DM}	900	А
Operating Junction and Storage Temperature			T _J , T _{stg}	-55 to + 175	°C
Source Current (Body Diode)			۱ _S	191	А
Single Pulse Drain–to–Source Avalanche Energy (I _{L(pk)} = 38 A)			E _{AS}	907	mJ
Lead Temperature for Soldering Purposes (1/8" from case for 10 s)		ΤL	260	°C	

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

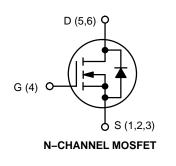
THERMAL RESISTANCE MAXIMUM RATINGS

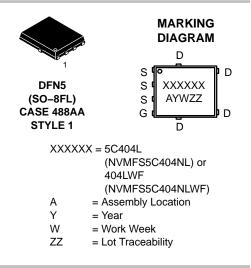
Parameter	Symbol	Value	Unit
Junction-to-Case - Steady State	R_{\thetaJC}	0.75	°C/W
Junction-to-Ambient - Steady State (Note 2)	R_{\thetaJA}	39	

1. The entire application environment impacts the thermal resistance values shown, they are not constants and are only valid for the particular conditions noted.

2. Surface-mounted on FR4 board using a 650 mm², 2 oz. Cu pad.

 Maximum current for pulses as long as 1 second is higher but is dependent on pulse duration and duty cycle.





ORDERING INFORMATION

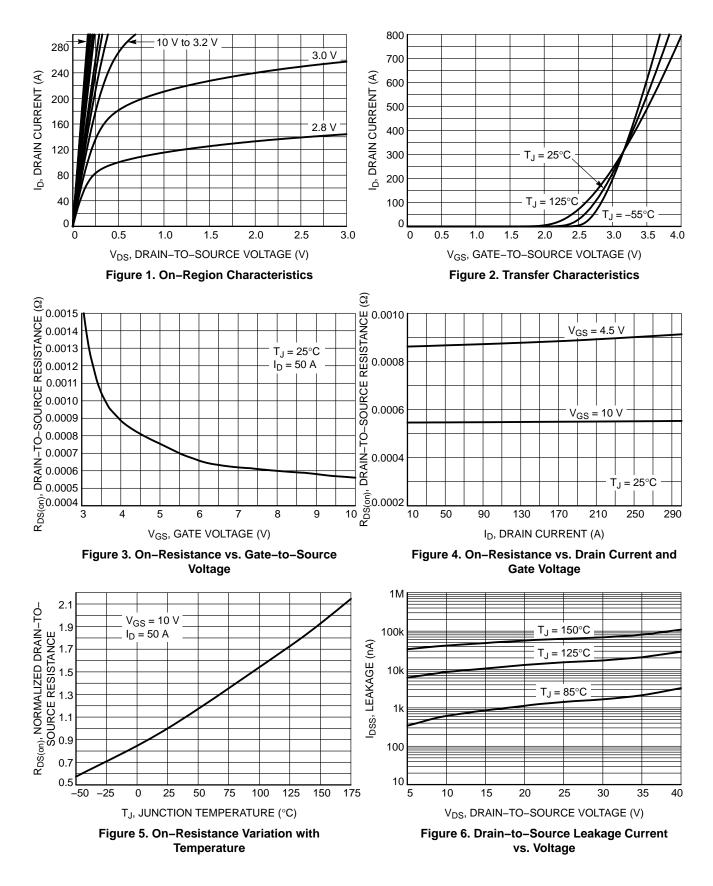
See detailed ordering, marking and shipping information in the package dimensions section on page 5 of this data sheet.

ELECTRICAL CHARACTERISTICS (T_J = 25° C unless otherwise specified)

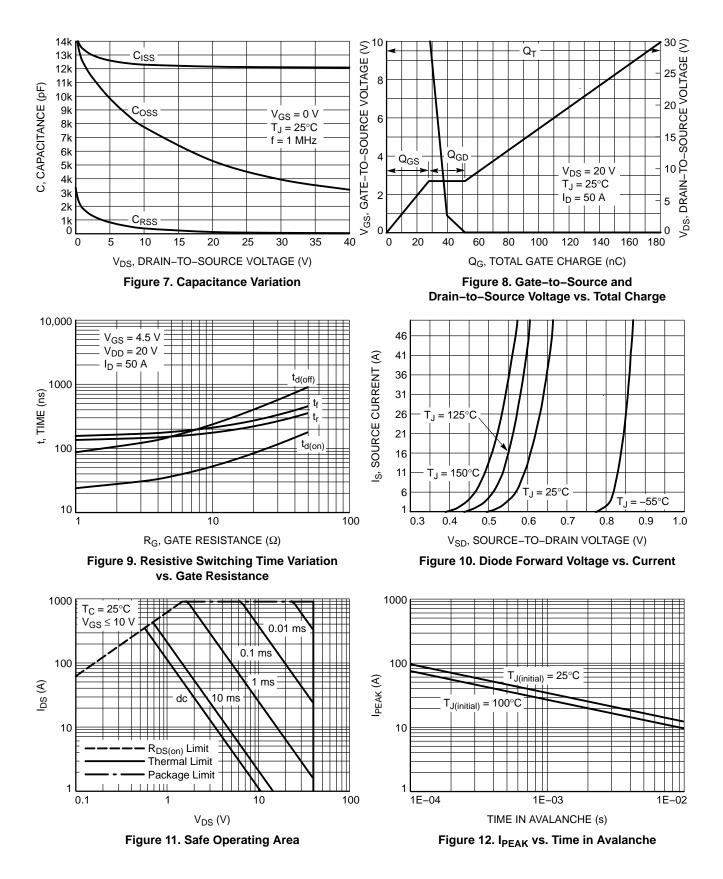
Parameter	Symbol	Test Condition		Min	Тур	Max	Unit
OFF CHARACTERISTICS							
Drain-to-Source Breakdown Voltage	V _{(BR)DSS}	V_{GS} = 0 V, I _D = 250 μ A		40			V
Drain-to-Source Breakdown Voltage Temperature Coefficient	V _{(BR)DSS} / T _J				21.6		mV/°C
Zero Gate Voltage Drain Current	I _{DSS}	$V_{GS} = 0 V,$	T _J = 25 °C			10	
	$V_{\rm DS} = 40 \text{ V}$		T _J = 125°C			250	μΑ
Gate-to-Source Leakage Current	I _{GSS}	V _{DS} = 0 V, V _{GS} = 20 V				100	nA
ON CHARACTERISTICS (Note 4)	-	• •				-	-
Gate Threshold Voltage	V _{GS(TH)}	$V_{GS} = V_{DS}, I_{D} = 250 \ \mu A$		1.2		2.0	V
Threshold Temperature Coefficient	V _{GS(TH)} /T _J				-6.2		mV/°C
Drain-to-Source On Resistance	R _{DS(on)}	V _{GS} = 10 V	I _D = 50 A		0.52	0.67	
		V _{GS} = 4.5 V	I _D = 50 A		0.75	1.0	mΩ
Forward Transconductance	9 _{FS}	V _{DS} =15 V, I _D = 50 A			270		S
CHARGES, CAPACITANCES & GATE RE	SISTANCE					-	
Input Capacitance	C _{ISS}	V _{GS} = 0 V, f = 1 MHz, V _{DS} = 25 V			12168		pF
Output Capacitance	C _{OSS}				4538		
Reverse Transfer Capacitance	C _{RSS}				79.8		
Total Gate Charge	Q _{G(TOT)}	V_{GS} = 4.5 V, V_{DS} = 20 V; I_{D} = 50 A			81		
Total Gate Charge	Q _{G(TOT)}	V _{GS} = 10 V, V _{DS} = 20 V; I _D = 50 A			181		
Threshold Gate Charge	Q _{G(TH)}	V _{GS} = 4.5 V, V _{DS} = 20 V; I _D = 50 A			8.5		nC
Gate-to-Source Charge	Q _{GS}				27.8		
Gate-to-Drain Charge	Q _{GD}				23.8		
Plateau Voltage	V _{GP}				2.7		V
SWITCHING CHARACTERISTICS (Note 5	5)					-	
Turn-On Delay Time	t _{d(ON)}			24			
Rise Time	tr	V _{CS} = 4.5 V. V _D	s = 20 V.		135		1
Turn-Off Delay Time	t _{d(OFF)}	$V_{GS} = 4.5 \text{ V}, V_{DS} = 20 \text{ V},$ $I_D = 50 \text{ A}, R_G = 1.0 \Omega$			87		- ns
Fall Time	t _f				157		
DRAIN-SOURCE DIODE CHARACTERIS	TICS						
Forward Diode Voltage	V _{SD}	V _{GS} = 0 V,	$T_J = 25^{\circ}C$		0.7	1.2	
	VGS = 0 V,	T _J = 125°C		0.61		- V	
Reverse Recovery Time	t _{RR}	V _{GS} = 0 V, dIS/dt = 100 A/µs, I _S = 50 A			97.4		ns
Charge Time	ta				46.5		
Discharge Time	t _b				50.9		
Reverse Recovery Charge	Q _{RR}				190		nC

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions. 4. Pulse Test: pulse width $\leq 300 \ \mu$ s, duty cycle $\leq 2\%$. 5. Switching characteristics are independent of operating junction temperatures.

TYPICAL CHARACTERISTICS



TYPICAL CHARACTERISTICS



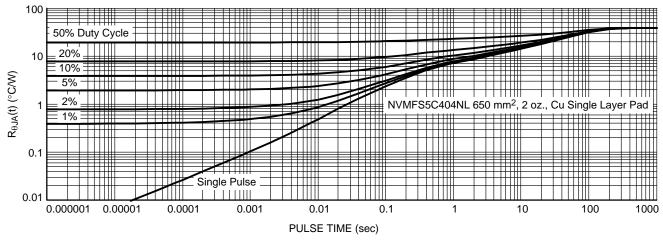


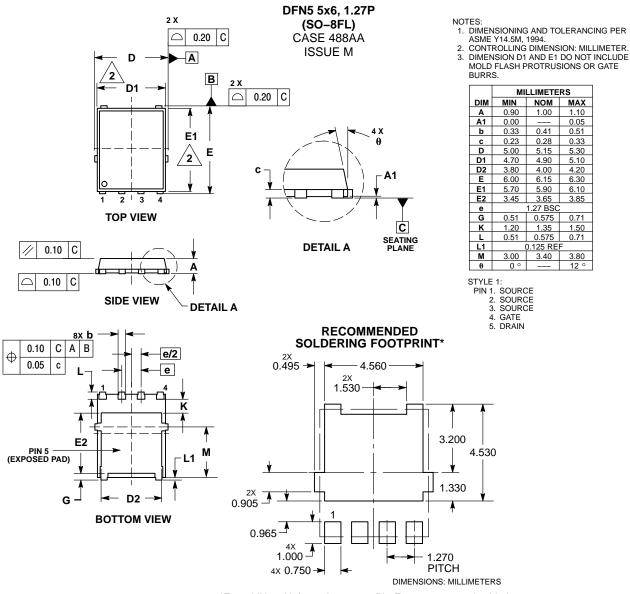
Figure 13. Thermal Characteristics

DEVICE ORDERING INFORMATION

Device	Marking	Package	Shipping [†]
NVMFS5C404NLT1G	5C404L	DFN5 (Pb–Free)	1500 / Tape & Reel
NVMFS5C404NLWFT1G	404LWF	DFN5 (Pb–Free, Wettable Flanks)	1500 / Tape & Reel
NVMFS5C404NLT3G	5C404L	DFN5 (Pb–Free)	5000 / Tape & Reel
NVMFS5C404NLWFT3G	404LWF	DFN5 (Pb–Free, Wettable Flanks)	5000 / Tape & Reel

+For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

PACKAGE DIMENSIONS



*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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